



TITLE: INTEGRATED CIRCUIT PACKAGE HAVING BYPASS CAPACITORS
COUPLED TO BOTTOM OF PACKAGE SUBSTRATE AND SUPPORTING
SURFACE MOUNTING TECHNOLOGY

INVENTOR(S): Behdad Jafari and Ray Chen

USSN: 10/717,342 ATTORNEY DOCKET #: NVID-P000730

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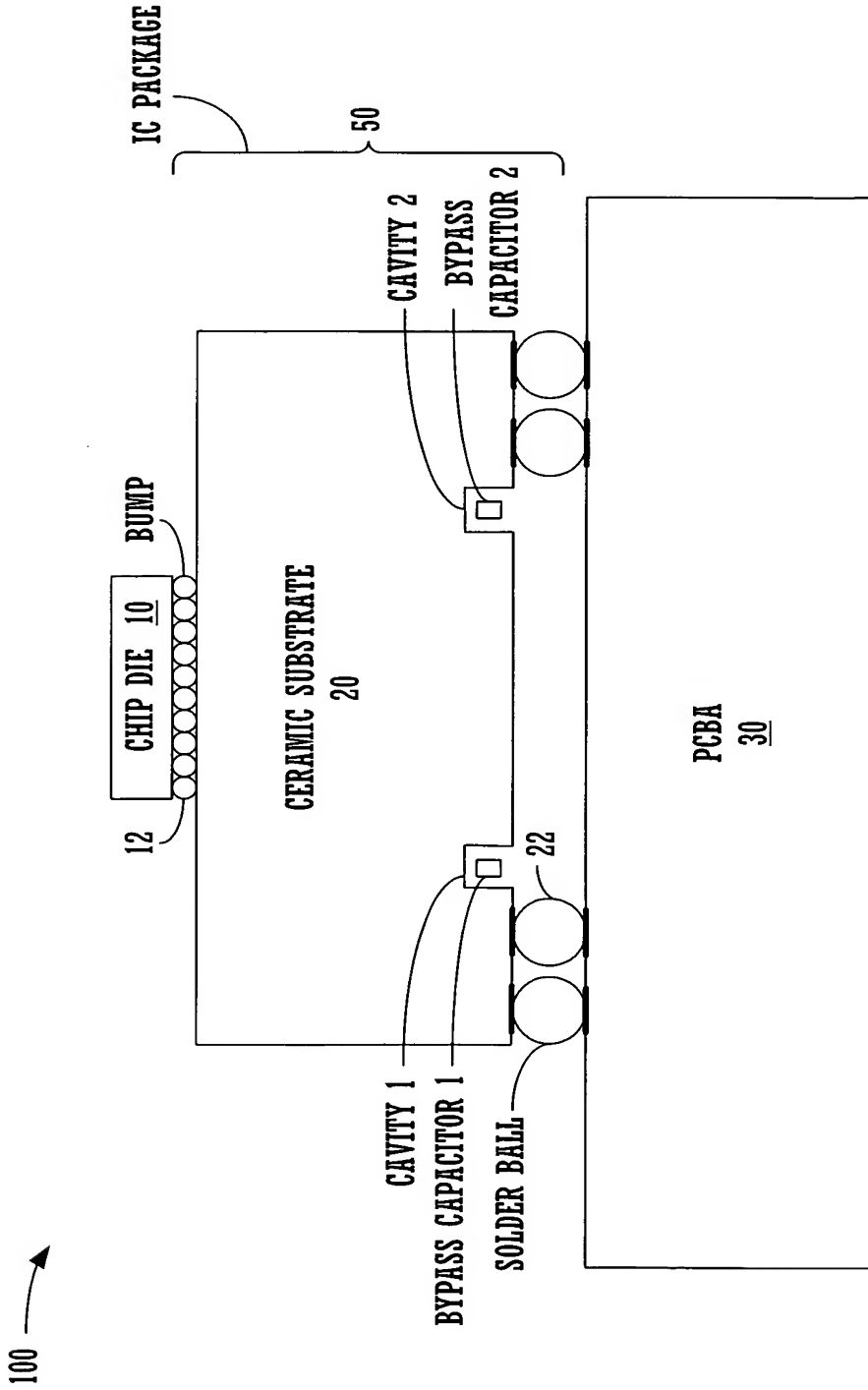
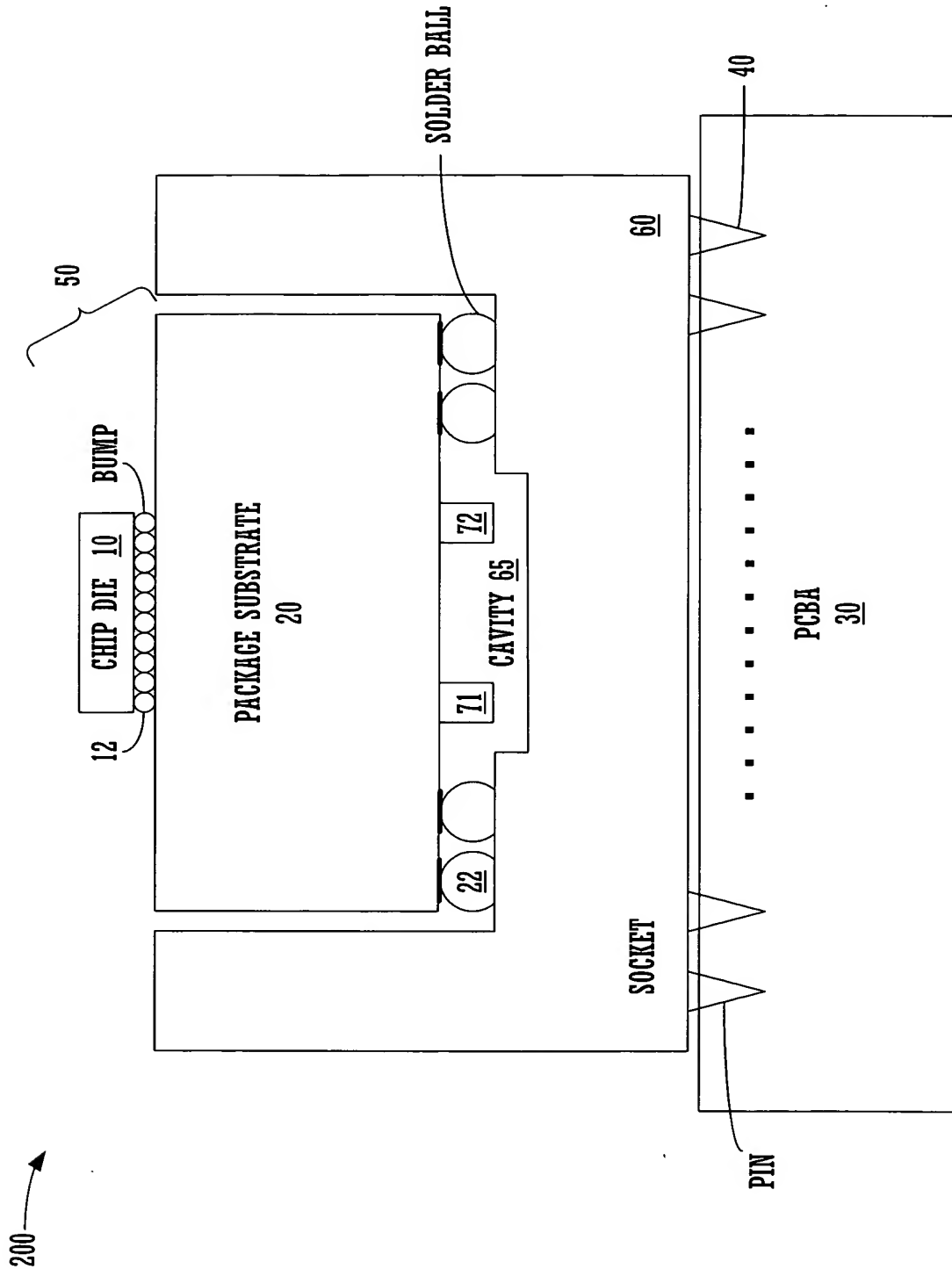


FIGURE 1
(Prior Art)





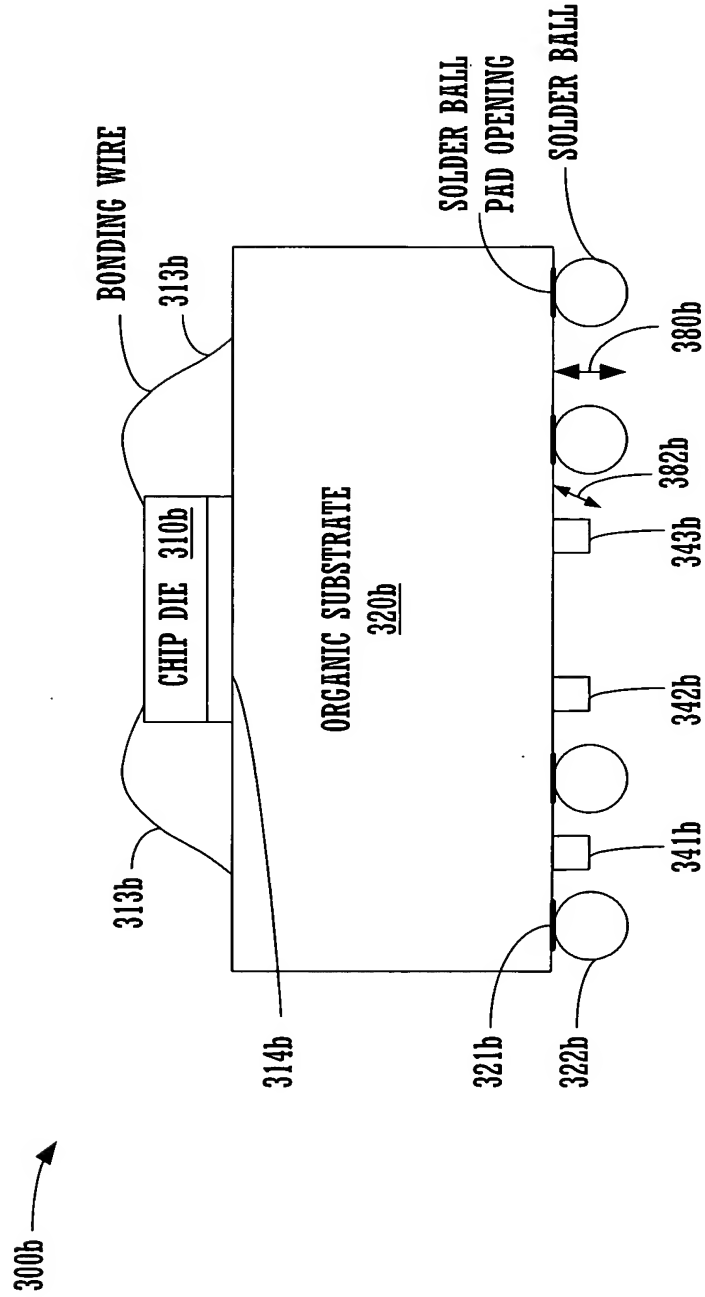


FIGURE 3B

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TOP VIEW

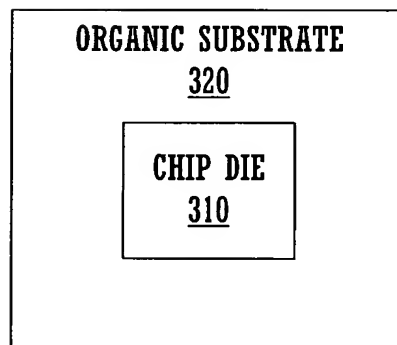


FIGURE 4A

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BOTTOM VIEW

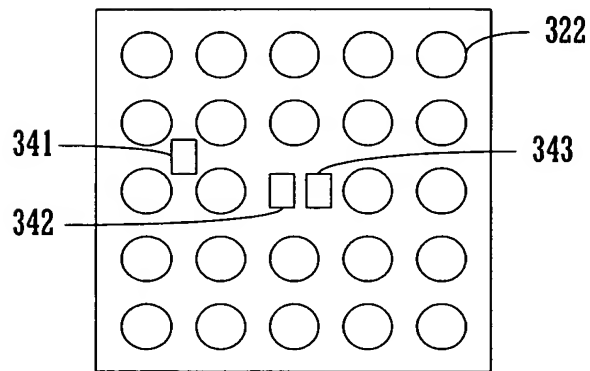
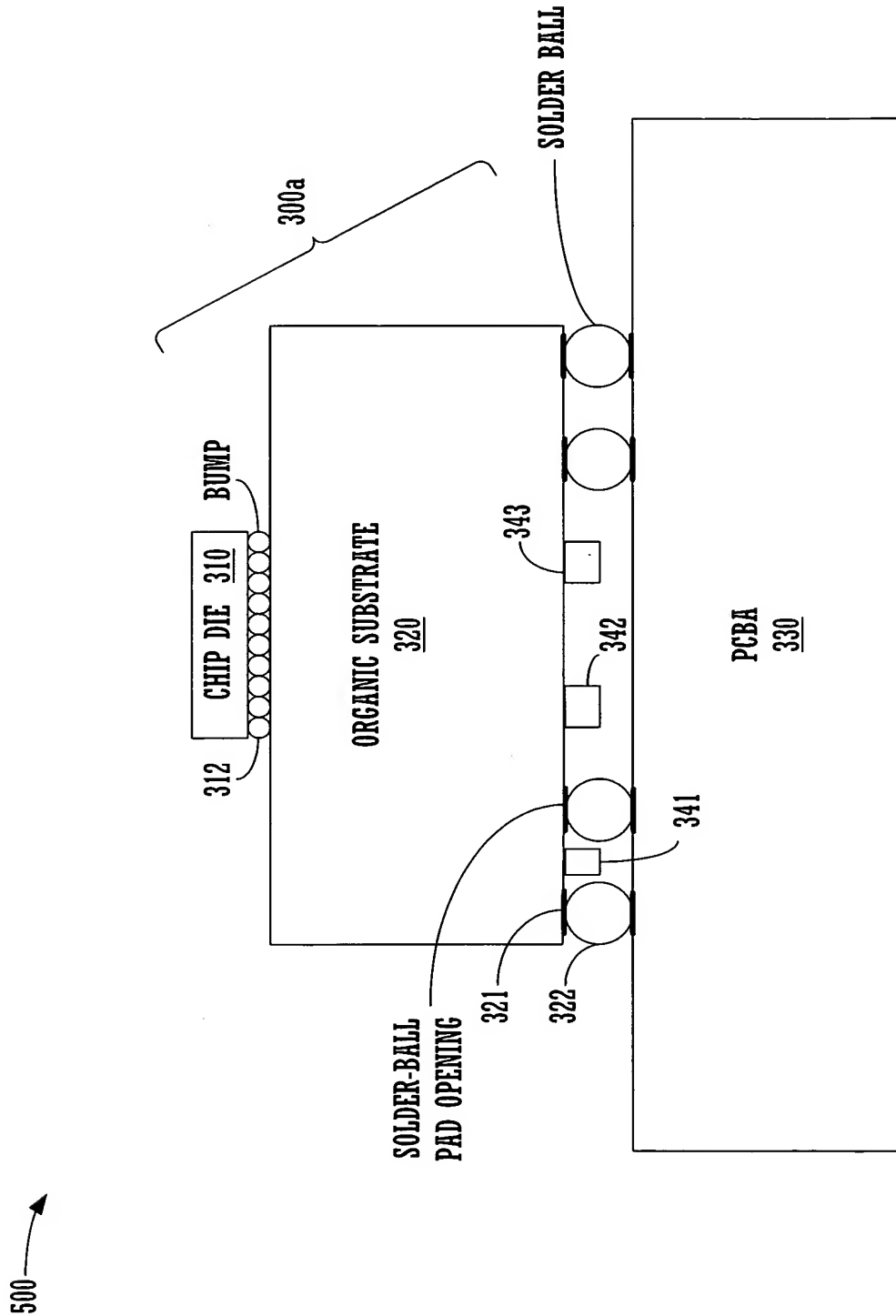


FIGURE 4B

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600

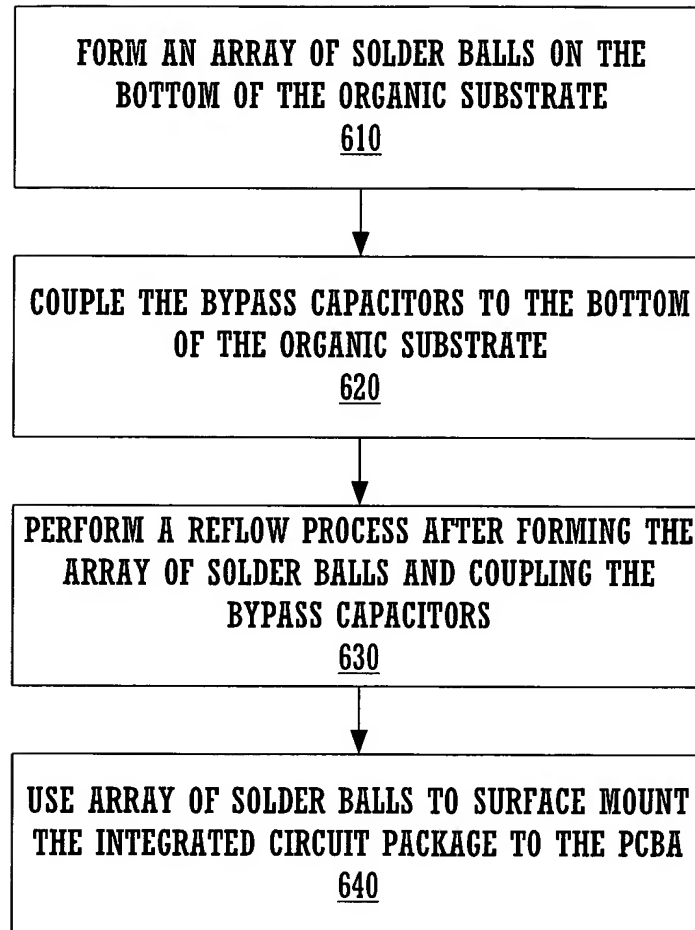


FIGURE 6